

Customer No.: 31561  
Application No.: 10/711,674  
Docket No.: 13689-US-PA

### AMENDMENTS

#### In The Claims:

Claim 1. (currently amended) A bonding pad for disposing on a chip, comprising:

a body having a first surface and a corresponding second surface and having a central region and corner regions, wherein the body is disposed on the chip, and the second surface of the body is in contact with the chip; and

~~at least one~~ a plurality of first protruding portions disposed on the first surface at the corner regions of the body; ; and

a second protruding portion disposed on the first surface in the central region of the body, wherein each of the first protruding portions extends to the central region from the corner region to connect to the second protruding portion.

#### **Claims 2-4. (cancelled)**

Claim 5. (currently amended) The bonding pad of claim 3 1, wherein the shape of the second protruding portion when viewed from the top against the first surface is selected from the group consisting of a cross-line shape, a circular shape, a circular ring shape, an ellipse shape, an ellipse ring shape, a polygonal shape, a polygonal ring shape, a linear shape, a geometrical shape and combinations thereof.

Claim 6. (currently amended) The bonding pad of claim 2 1, wherein the materials for the body, the first protruding portion and the second protruding portion are identical.

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Claim 7. (previously presented) The bonding pad of claim 1, wherein the materials for the body and the first protruding portion are identical.

Claim 8. (original) The bonding pad of claim 1, wherein the material constituting the bonding pad comprises aluminum.

Claim 9. (original) The bonding pad of claim 1, wherein the body has a four-sided geometric shape.

Claim 10. (currently amended) A chip structure, comprising:

a chip having an active surface;

at least one bonding pad disposed on the active surface of the chip, the bonding pad including:

a body having a first surface and a corresponding second surface and having a central region and corner regions, wherein the body is disposed on the chip, and the second surface of the body is in contact with the chip; and

~~at least one~~ a plurality of first protruding portions disposed on the first surface at the corner regions of the body; ~~and~~

a second protruding portion disposed on the first surface in the central region of the body, wherein each of the first protruding portions extends to the central region from the corner region to connect to the second protruding portion.

Claims 11-13. (cancelled)

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Claim 14. (currently amended) The chip structure of claim ~~12~~ 10, wherein the shape of the second protruding portion when viewed from the top against the first surface is selected from the group consisting of a cross-line shape, a circular shape, a circular ring shape, an ellipse shape, an ellipse ring shape, a polygonal shape, a polygonal ring shape, a linear shape, a geometrical shape and combinations thereof.

Claim 15. (currently amended) The chip structure of claims ~~11~~ 10, wherein the materials for the body, the first protruding portion and the second protruding portion are identical.

Claim 16. (previously presented) The chip structure of claims 10, wherein the materials for the body and the first protruding portion are identical.

Claim 17. (original) The chip structure of claim 10, wherein the material constituting the bonding pad comprises aluminum.

Claim 18. (original) The chip structure of claim 10, wherein the body has a four-sided geometric shape.

Claim 19. (original) The chip structure of claim 10, further comprising a passivation layer disposed on the active surface of the chip that also covers the peripheral region of the bonding pad but leaves the central region of the bonding pad exposed.

Claim 20. (original) The chip structure of claim 10, further comprising at least a bump disposed on and electrically connected with the bonding pad.

Claim 21. (currently amended) A pad for disposing on a chip, comprising:

a body having a central region and corner regions; and

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~~at least one~~ a plurality of first protruding portions disposed on the corner regions  
of the body; and

a second protruding portion disposed on the central region of the body, wherein  
each of the first protruding portions extends to the central region from the corner region to  
connect to the second protruding portion.

**Claim 22. (cancelled)**

**Claim 23. (original)** A display apparatus comprising a device which includes the pad of  
claim 21.

**Claims 24-25. (cancelled)**

**Claim 26. (original)** A device comprising the pad of claim 21.

**Claims 27-28. (cancelled)**